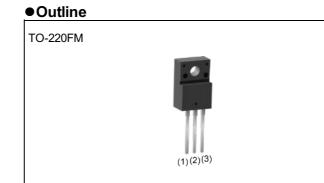


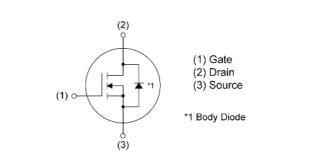
| V _{DSS} | 600V |
|----------------------------|--------|
| R _{DS(on)} (Max.) | 0.780Ω |
| I _D | ±7A |
| P _D | 46W |



Features

- 1) Fast reverse recovery time (trr)
- 2) Low on-resistance
- 3) Fast switching speed
- 4) Drive circuits can be simple
- 5) Pb-free plating ; RoHS compliant

Inner circuit



Application

Switching

Packaging specifications

| Packing | Tube |
|---------------------------|----------|
| Packing code | C7 G |
| Marking | R6007JNX |
| Basic ordering unit (pcs) | 2000 |

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|--|--------------------|-------------|------|
| Drain - Source voltage | V _{DSS} | 600 | V |
| Continuous drain current ($T_c = 25^{\circ}C$) | I _D *1 | ±7 | А |
| Pulsed drain current | I _{DP} *2 | ±21 | А |
| Gate - Source voltage | V _{GSS} | ±30 | V |
| Avalanche current, single pulse | I _{AS} *3 | 1.6 | Α |
| Avalanche energy, single pulse | E _{AS} *3 | 132 | mJ |
| Power dissipation $(T_c = 25^{\circ}C)$ | P _D | 46 | W |
| Junction temperature | Tj | 150 | °C |
| Operating junction and storage temperature range | T _{stg} | -55 to +150 | °C |

•Thermal resistance

| Deremeter | Cumph of | Values | | | Lincit |
|--|-------------------|--------|------|------|--------|
| Parameter | Symbol | Min. | Тур. | Max. | Unit |
| Thermal resistance, junction - case | R _{thJC} | - | - | 2.70 | °C/W |
| Thermal resistance, junction - ambient | R _{thJA} | - | - | 70 | °C/W |
| Soldering temperature, wavesoldering for 10s | T _{sold} | - | - | 265 | °C |

•Electrical characteristics (T_a = 25°C)

| Deremeter | Sumpleal | Conditions | Values | | | Linit | |
|--|--|---|--------|-------|-------|-------|--|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit | |
| Drain - Source breakdown voltage | $V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$ | | 600 | - | - | V | |
| Zero gate voltage drain current | I _{DSS} | $V_{DS} = 600V, V_{GS} = 0V$ $T_j = 25^{\circ}C$ | - | - | 100 | μA | |
| Gate - Source leakage current | I _{GSS} | V_{GS} = ±30V, V_{DS} = 0V | - | - | ±100 | nA | |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 1.0 \text{mA}$ | 5.0 | 6.0 | 7.0 | V | |
| Static drain - source on - state resistance | R _{DS(on)} *5 | V _{GS} = 15V, I _D = 3.5A T _j = 25°C | - | 0.600 | 0.780 | Ω | |
| Gate resistance | R _G | f = 1MHz, open drain | - | 2.9 | - | Ω | |



• Electrical characteristics (T_a = 25°C)

| Deremeter | Cumph of | Conditions | Values | | | Unit |
|---|---------------------------------|---------------------------------------|--------|------|------|------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Input capacitance | C _{iss} | V _{GS} = 0V | - | 475 | - | |
| Output capacitance | C _{oss} | V _{DS} = 100V | - | 30 | - | |
| Reverse transfer capacitance | C _{rss} | f = 1MHz | - | 1.4 | - | _ |
| Effective output capacitance energy related | C _{o(er)} ⁶ | V _{GS} = 0V | - | 23 | - | pF |
| Effective output capacitance time related | C _{o(tr)} ⁷ | $V_{DS} = 0V$ to 480V | - | 90 | - | |
| Turn - on delay time | t _{d(on)} *5 | $V_{DD} \simeq 300$ V, V_{GS} = 15V | - | 17 | - | |
| Rise time | t _r *5 | I _D = 3.5A | - | 15 | - | 20 |
| Turn - off delay time | $t_{d(off)}^{*5}$ | $R_L \simeq 86.6\Omega$ | - | 32 | - | ns |
| Fall time | t _f *5 | R _G = 10Ω | - | 25 | - | |

• Gate charge characteristics ($T_a = 25^{\circ}C$)

| Deremeter | Cumphal | Conditions | Values | | | Unit |
|----------------------|---------------------------|-----------------------------------|--------|------|------|------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Total gate charge | Q_g^{*5} | $V_{DD} \simeq 300 V$ | - | 17.5 | - | |
| Gate - Source charge | Q_{gs}^{*5} | I _D = 7A | - | 5.1 | - | nC |
| Gate - Drain charge | ${\sf Q}_{\sf gd}{}^{*5}$ | V _{GS} = 15V | - | 6.4 | - | |
| Gate plateau voltage | V _(plateau) | $V_{DD} \simeq 300V$, $I_D = 7A$ | - | 9.1 | - | V |

*1 Limited only by maximum temperature allowed.

*2 Pw \leq 10µs, Duty cycle \leq 1%

*3 L \simeq 100mH, V_{DD} = 50V, R_G = 25 Ω , starting T_i = 25°C

- *4 Tc=25°C
- *5 Pulsed
- *6 Co(er) is a fixed capacitance that gives the same stored energy as Coss while V_{DS} is rising from 0 to 80% V_{DSS} .
- *7 Co(tr) is a fixed capacitance that gives the same charging time as Coss while V_{DS} is rising from 0 to 80% V_{DSS} .



•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

| Parameter | Sympol | Conditions | Values | | | Unit |
|-------------------------------|----------------------|---|--------|------|------|------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Source current | I _S *1 | $T = 25^{\circ}$ | - | - | 7 | А |
| Pulsed source current | ۱ _{SP} *2 | T _C = 25°C | - | - | 21 | А |
| Source-Drain voltage | V_{SD}^{*5} | V _{GS} = 0V, I _S = 7A | - | - | 1.7 | V |
| Reverse recovery time | t _{rr} *5 | | - | 60 | - | ns |
| Reverse recovery charge | Q _{rr} *5 | I _S = 7Α di/dt = 100Α/μs | - | 170 | - | nC |
| Peak reverse recovery current | ۱ <mark>, *</mark> 5 | | - | 6.5 | - | А |



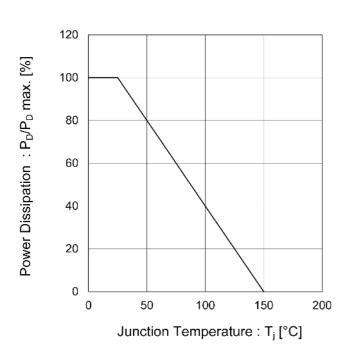
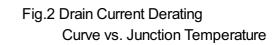


Fig.1 Power Dissipation Derating Curve



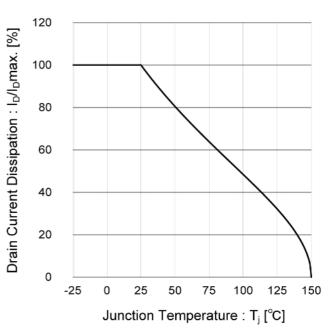


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Normalized Transient Thermal Resistance : r(t) 10 T_a = 25°C Single Pulse $R_{th(ch-c)(t)} = r_{(t)} \times R_{th(ch-c)}$ $R_{th(ch-c)} = 2.70^{\circ}C/W$ 1 0.1 top D = 1 D = 0.5 D = 0.1D = 0.05 D = 0.01D = Single 0.01 0.0001 0.001 0.01 0.1 1 10 Pulse Width : Pw [s]

Fig.4 Maximum Safe Operating Area

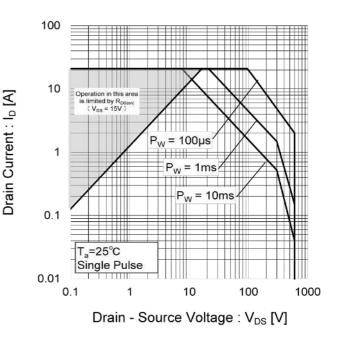
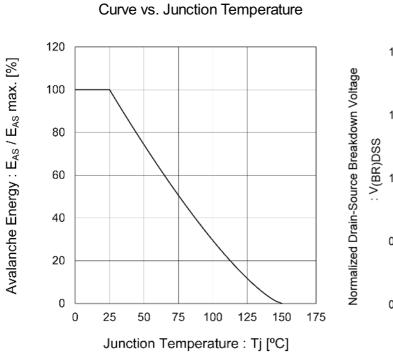
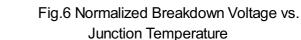




Fig.5 Avalanche Energy Derating





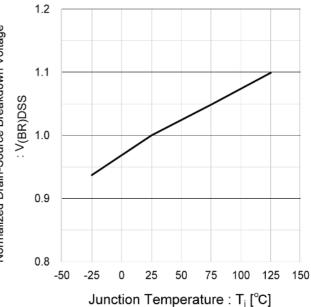


Fig.7 Typical Output Characteristics(I)

Drain Current : I_D [A]

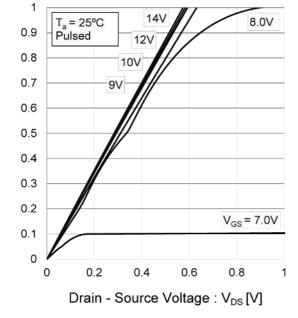
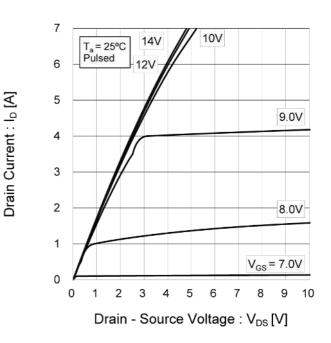


Fig.8 Typical Output Characteristics(II)





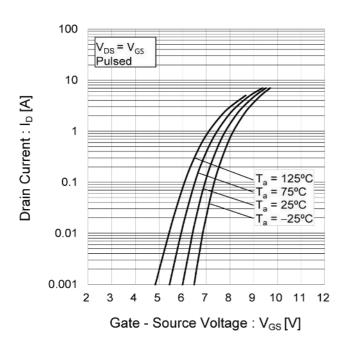


Fig.11 Static Drain - Source On - State

Resistance vs. Gate Source Voltage

Fig.9 Typical Transfer Characteristics

Fig.10 Normalized Gate Threshold . Voltage vs Junction Temperature

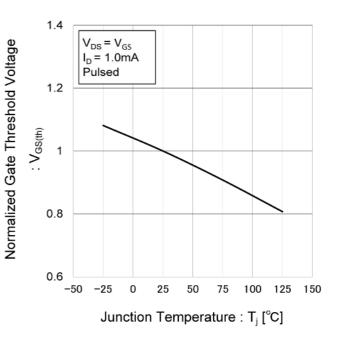
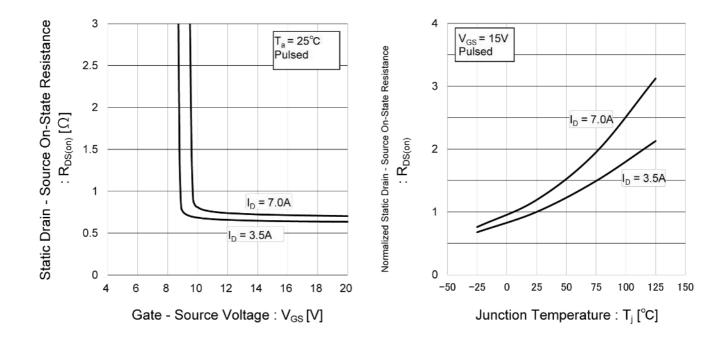


Fig.12 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature





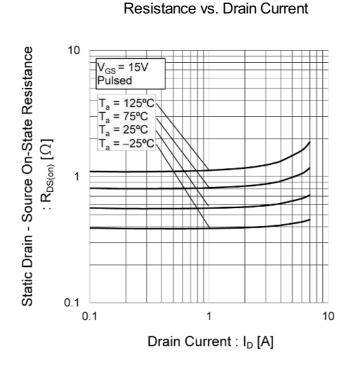


Fig.13 Static Drain - Source On - State

Fig.14 Typical Capacitance vs. Drain - Source Voltage

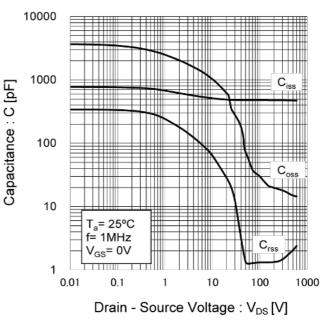
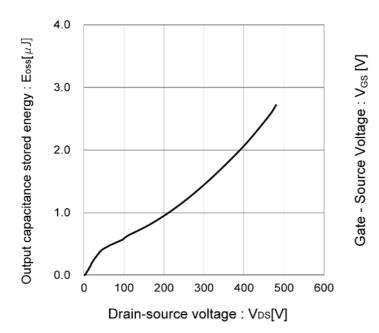
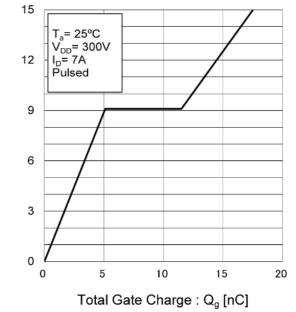


Fig.15 Typical Coss Stored Energy

Fig.16 Typical Gate Charge







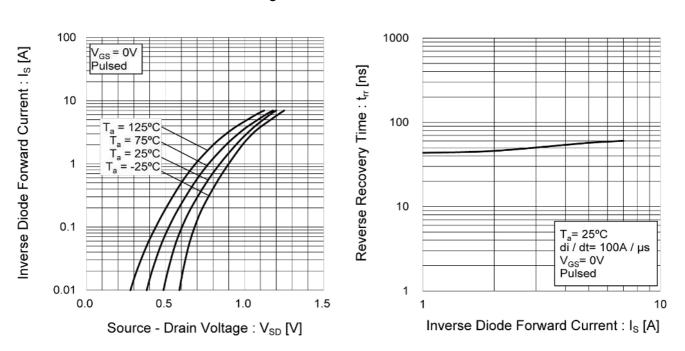
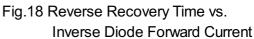


Fig.17 Inverse Diode Forward Current vs. Source - Drain Voltage





Measurement circuits



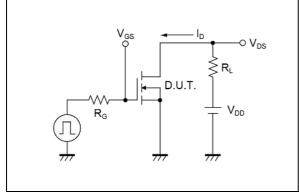


Fig.2-1 Gate Charge Measurement Circuit

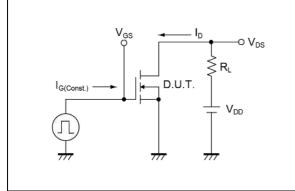


Fig.3-1 Avalanche Measurement Circuit

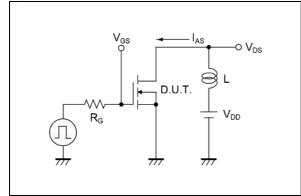


Fig.4-1 Diode Recovery Measurement Circuit

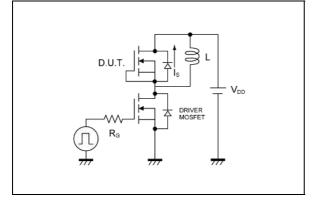


Fig.1-2 Switching Waveforms

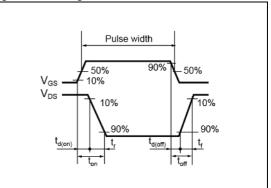


Fig.2-2 Gate Charge Waveform

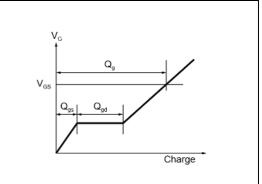


Fig.3-2 Avalanche Waveform

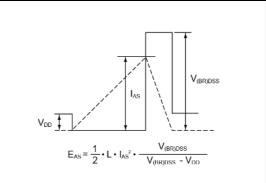
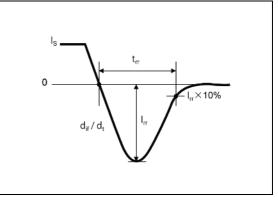


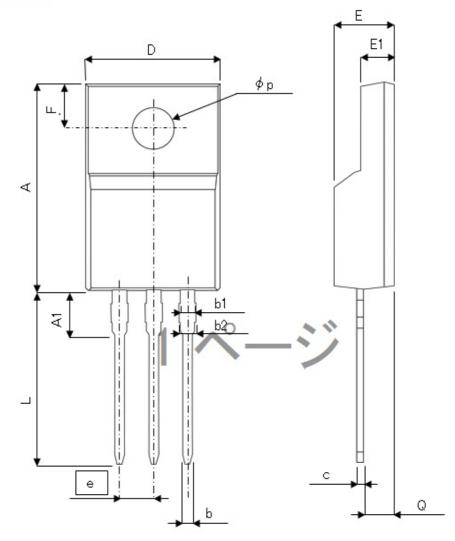
Fig.4-2 Diode Recovery Waveform





Dimensions

TO-220FM



| DIM | MILIMETERS | | INCH | IES |
|-----|------------|-------|-------|-------|
| DIM | MIN | MAX | MIN | MAX |
| А | 15.67 | 16.27 | 0.617 | 0.641 |
| A1 | 3.03 | 3.43 | 0.119 | 0.135 |
| Ь | 0.70 | 0.95 | 0.028 | 0.037 |
| Ь1 | 1.00 | 1.40 | 0.039 | 0.055 |
| ь2 | 1.10 | 1.50 | 0.043 | 0.059 |
| C | 0.45 | 0.65 | 0.018 | 0.026 |
| D | 9.90 | 10.30 | 0.390 | 0.406 |
| E | 4.60 | 5.00 | 0.181 | 0.197 |
| E1 | 2.44 | 2.74 | 0.096 | 0.108 |
| e | 2.5 | 54 | 0.10 | 00 |
| F | 3.10 | 3.50 | 0.122 | 0.138 |
| L | 12.6 | 13.6 | 0.496 | 0.535 |
| p | 2.98 | 3.38 | 0.117 | 0.133 |
| Q | 2.25 | 3.25 | 0.089 | 0.128 |

Dimension in mm / inches



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| (Note1) Medical Equipment Classification of the Specific Applications |
|---|
|---|

| JAPAN | USA | EU | CHINA |
|--------|----------|------------|---------|
| CLASSⅢ | CLASSⅢ | CLASS II b | CLASSII |
| CLASSⅣ | CLASSIII | CLASSⅢ | CLASSI |

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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